

IRFS240B

200V N-Channel MOSFET

General Description

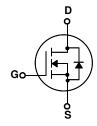
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supplies, DC-AC converters for uninterrupted power supply and motor control.

Features

- 12.8A, 200V, $R_{DS(on)}$ = 0.18 Ω @V_{GS} = 10 V Low gate charge (typical 45 nC)
- Low Crss (typical 45 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		IRFS240B	Units
V _{DSS}	Drain-Source Voltage		200	V
I _D	Drain Current - Continuous (T _C = 25°C	C)	12.8	Α
	- Continuous (T _C = 100	°C)	8.1	Α
I _{DM}	Drain Current - Pulsed	(Note 1)	51.2	Α
V _{GSS}	Gate-Source Voltage		± 30	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	250	mJ
I _{AR}	Avalanche Current	(Note 1)	12.8	Α
E _{AR}	Repetitive Avalanche Energy	(Note 1)	7.3	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns
P_D	Power Dissipation (T _C = 25°C)		73	W
	- Derate above 25°C		0.59	W/°C
T _J , T _{STG}	Operating and Storage Temperature Ran	ge	-55 to +150	°C
T _L	Maximum lead temperature for soldering 1/8" from case for 5 seconds	purposes,	300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.7	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units	
Off Cha	aracteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		200			V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced	to 25°C		0.2		V/°C
I _{DSS}	7 0	V _{DS} = 200 V, V _{GS} = 0 V				10	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 160 V, T _C = 125°C				100	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$		2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 6.4 A			0.145	0.18	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 6.4 A	(Note 4)		11.3		S
Dynam i C _{iss}	ic Characteristics Input Capacitance				1300	1700	pF
C _{oss}	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$			175	230	рF
C _{rss}	Reverse Transfer Capacitance	f = 1.0 MHz			45	60	рF
-133	Therefore Trainers Capacitaines				.0		ρ.
Switchi	ng Characteristics						
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 100 \text{ V}, I_{D} = 18 \text{ A},$ $R_{G} = 25 \Omega$			20	50	ns
t _r	Turn-On Rise Time				145	300	ns
t _{d(off)}	Turn-Off Delay Time				145	300	ns
t _f	Turn-Off Fall Time		(Note 4, 5)		110	230	ns
Qg	Total Gate Charge	$V_{DS} = 160 \text{ V}, I_{D} = 18 \text{ A},$			45	58	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 10 V			6.5		nC
Q_{gd}	Gate-Drain Charge		(Note 4, 5)		22		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings	6				
I _S	Maximum Continuous Drain-Source Did	ode Forward Current				12.8	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F	orward Current				51.2	Α
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 12.8 \text{ A}$				1.5	٧
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_S = 18 \text{ A},$			195		ns
Q _{rr}	Reverse Recovery Charge	$dl_{F}/dt = 100 \text{ A/}\mu\text{s} $ (Note 4)			1.47		μС

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 2.3mH, I_{AS} = 12.8A, V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25°C 3. I_{SD} \leq 18A, di/dt \leq 300A/µs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300µs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

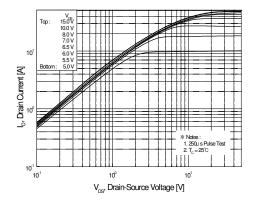


Figure 1. On-Region Characteristics

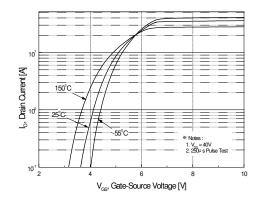


Figure 2. Transfer Characteristics

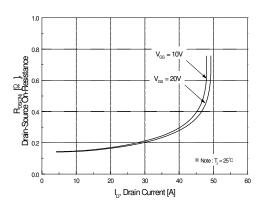


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

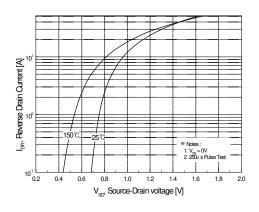


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

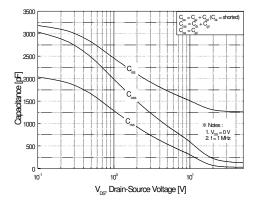


Figure 5. Capacitance Characteristics

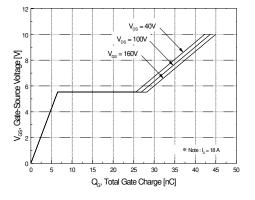
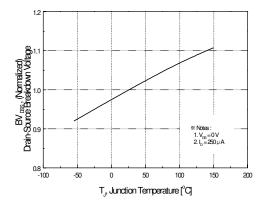


Figure 6. Gate Charge Characteristics

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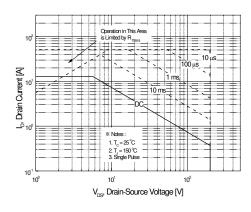




30 25 (08) 10 25 (08) 10

Figure 7. Breakdown Voltage Variation vs Temperature

Figure 8. On-Resistance Variation vs Temperature



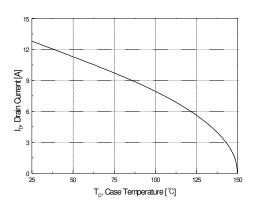


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs Case Temperature

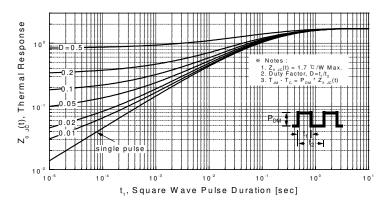
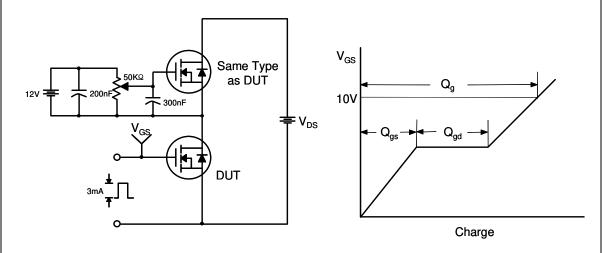


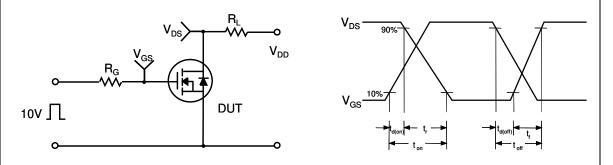
Figure 11. Transient Thermal Response Curve

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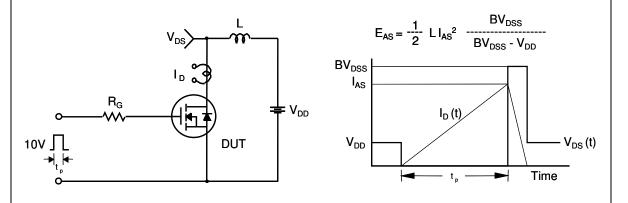
Gate Charge Test Circuit & Waveform



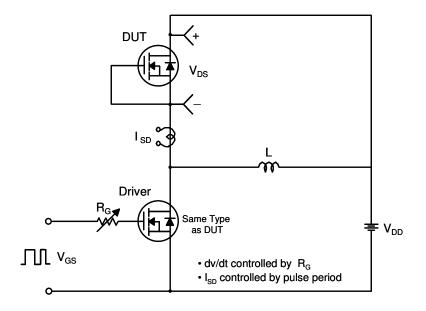
Resistive Switching Test Circuit & Waveforms

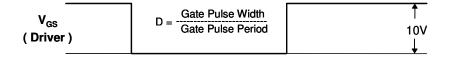


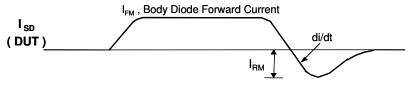
Unclamped Inductive Switching Test Circuit & Waveforms



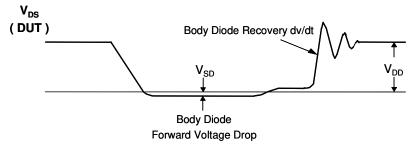
Peak Diode Recovery dv/dt Test Circuit & Waveforms

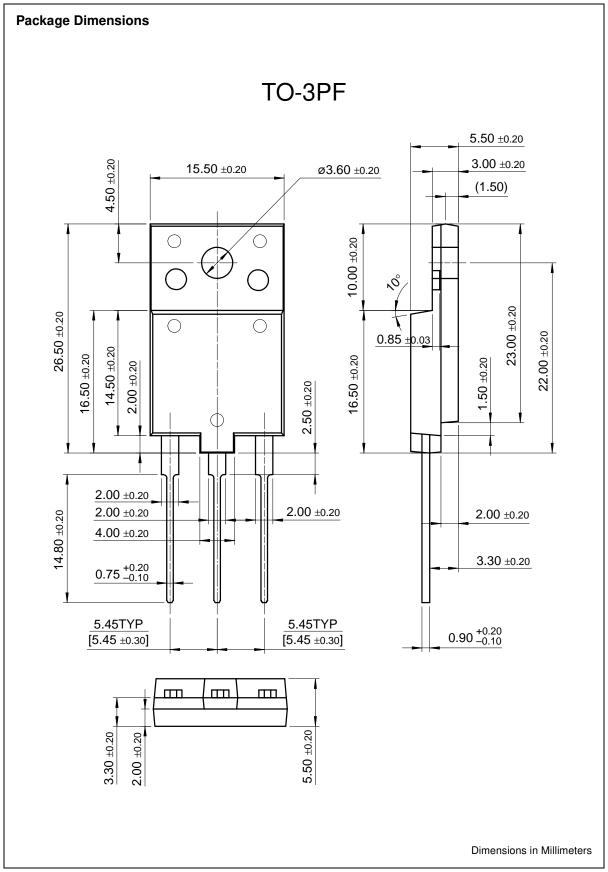






Body Diode Reverse Current





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IRFS240B

200V N-Channel B-FET / Substitute of IRFS240 & IRFS240A

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Product status/pricing/packaging



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Indicates product with Pb-free second-level interconnect. For more information click here.

Package marking information for product IRFS240B is available. Click here for more information.

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Qualification Support

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